[CLAIMS]

[Claim 1]

A manufacturing method of a mounting structure, the method comprising:

a step of preparing a mounting member including a first circuit member and a plurality of second circuit members placed on the first circuit member via bumps, the mounting member having a space between the first circuit member and the second circuit member;

a step of preparing a sheet having a space maintaining layer;

a disposing step of disposing the sheet on the mounting member such that the space maintaining layer faces the second circuit members; and

a sealing step of pressing the sheet against the first circuit member and heating the sheet, to seal the second circuit members so as to maintain the space, and to cure the sheet, wherein

the bumps are solder bumps, and

the space maintaining layer after curing has a glass transition temperature of higher than 125 °C, and a coefficient of thermal expansion at 125 °C or lower of 20 ppm/K or less,

the space maintaining layer has a loss tangent $\tan\delta 1_t$ of 1 or less, at a temperature t when the second circuit members are sealed.

[Claim 2]

The manufacturing method of claim 1, wherein

the sheet further includes a stress release layer, and

the stress release layer after curing has a loss tangent $\tan\delta 2$, in a temperature range equal to or lower than a glass transition temperature of the stress release layer after curing, being 0.02 or more at 40 °C or higher.

[Claim 3]

The manufacturing method of claim 2, wherein the stress release layer has a loss tangent $\tan\delta 2_t$ of greater than 3 and a storage shear modulus of 1×10^3 Pa or more, at the temperature t when the second circuit members are sealed.

[Claim 4]

The manufacturing method of any one of claims 1 to 3, wherein the first circuit member is a ceramic substrate.

[Claim 5]

A manufacturing method of an individualized mounting structure, the method comprising a step of dicing the mounting structure obtained by the manufacturing method of claim 1, to individualize the second circuit members.

[Claim 6]

A sheet for sealing a mounting member including a first circuit member and a plurality of second circuit members placed on the first circuit member via solder bumps, the mounting member having a space between the first circuit member and the second circuit member, the sheet comprising

a space maintaining layer, wherein

the space maintaining layer after curing has a glass transition temperature of higher than 125 °C, and a coefficient of thermal expansion at 125 °C or lower of 20 ppm/K or less,

the space maintaining layer has a loss tangent $\tan\delta 1_t$ of 1 or less, at a temperature t when the second circuit members are sealed.

[Claim 7]

The sheet of claim 6, further comprising a stress release layer, wherein

the space maintaining layer is disposed at least on one outermost side, and

the stress release layer after curing has a loss tangent tanδ2, in a temperature range equal to or lower than a glass transition temperature of the stress release layer after curing, being 0.02 or more at 40 °C or higher.

[Claim 8]

The sheet of claim 7, wherein the stress release layer has a loss tangent $\tan\delta 2_t$ of greater than 3 and a storage shear modulus of 1×10^3 Pa or more, at the temperature t when the second circuit members are sealed.